

Electronic Patent Application Fee Transmittal

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|--|---|-----------------|---------------|-----------------------------|
| Application Number: | 10616097 | | | |
| Filing Date: | 08-Jul-2003 | | | |
| Title of Invention: | Multiple-step electrodeposition process for direct copper plating on barrier metals | | | |
| First Named Inventor/Applicant Name: | Zhi-Wen Sun | | | |
| Filer: | Keith Patrick Taboada | | | |
| Attorney Docket Number: | AMAT/8241/CMP/ECP/RKK | | | |
| Filed as Large Entity | | | | |
| Utility under 35 USC 111(a) Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |
| Extension - 1 month with \$0 paid | 1251 | 1 | 130 | 130 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 130 |